REV LETTER: E
PAGE NO: 1 OF 1
PART NUMBER:

LP-MSM014

Polymer PTC Devices

Surface mount fuses

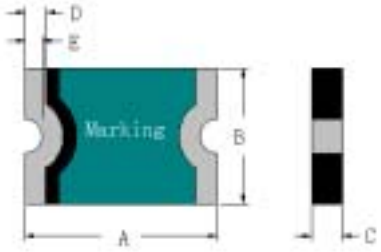
Shanghai Wayon Thermo/Electro Materials Co.,Ltd.
4th Floor, No.201, New Jinqiao Road, Shanghai 201206,China
Tel: 86-21- 50320161 58995165 Fax: 86-21-50320266
E-mail: market@way-on.com ***Http://www.way-on.com***

Features

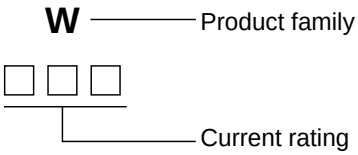
- ☐ Small size of 1812
- ☐ Fast tripping resettable circuit protection
- ☐ Surface mount packaging for automated assembly
- ☐ Agency Recognition: UL、CSA、TUV

Product Dimensions (mm)

Part number	A	B	C	D	E
	Max.	Max.	Max.	Max.	Min.
LP-MSM014	4.73	3.41	0.81	0.60	0.30



Part Marking System

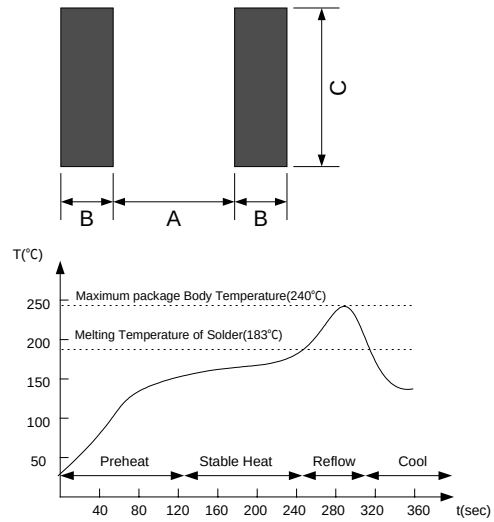


Electrical Characteristics

Part number	I_H	I_T	V_{max}	I_{max}	T_{trip}		Pd_{typ}	R_{min}	R_{1max}
	(A)	(A)	(V)	(A)	Current(A)	Time(S)	(W)	(Ω)	(Ω)
LP-MSM014	0.14	0.34	60	10	1.5	0.15	1.0	0.70	6.00

I_H=Hold current: maximum current at which the device will not trip at 25℃ still air.
I_T=Trip current: minimum current at which the device will always trip at 25℃ still air.
V_{max}=Maximum voltage device can withstand without damage at rated current.
I_{max}=Maximum fault current device can withstand without damage at rated voltage.
T_{trip}=Maximum time to trip(s) at assigned current.
Pd_{typ}=Typical power dissipation: typical amount of power dissipated by the device when in state air environment.
R_{min}=Minimum device resistance at 25℃ prior to tripping.
R_{1max}=Maximum device resistance measured in the nontripped state 1 hour post reflow.

Solder Reflow Recommendations



Solder Pad Layouts

Part number	A	B	C
	(mm)	(mm)	(mm)
LP-MSM014	3.45	1.78	3.15

* Recommended reflow methods: IR, Vapor phase oven, hot air oven, wave solder.
* Devices can be cleaned using standard industry methods and solvents.

Notes:
If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Tape & Reel: 2000pcs per reel.